

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) An optoelectronic component based on [[the]] a surface mount technology, [[said]] the optoelectronic component comprising:
[[a]] an electrically conductive material (1), frame to form a base for an assembly;
an opaque plastic material (2), and to form a housing for the assembly;
a cavity [(5,)] formed within the plastic material;
at least one protrusion extending from a side surface of the housing to provide
heat dissipation; and
at least one optoelectronic chip mounted in the cavity,
~~wherein the said electrically conductive material (1) serves as a base for the assembly, the said opaque plastic material (2) provides a housing for the whole component, and the said cavity (5) is located within the plastic material where an optoelectronic chip (3) is mounted in wherein the base protrudes from a middle portion to a bottom surface of the optoelectronic component, the bottom surface of the optoelectronic component providing external mounting connection terminals.~~

2. (Currently amended) [[An]] The optoelectronic component as claimed in claim 1, wherein the cavity [(5)] is filled with a transparent [[and]] or translucent resin material.

3. (Currently amended) [[An]] The optoelectronic component as claimed in claim 1, wherein an electrical connection[[s]] between the at least one optoelectronic chip [[(3)]] and the base material is provided [[with]] by a metallic wire [[(4)]].

4. (Currently amended) [[An]] The optoelectronic component as claimed in claim 1, wherein ~~initial base material provides connecting terminals to the external mounting connection terminals are provided for connecting to external sub-systems such as PCBs.~~

5. (Canceled)

6. (Currently amended) [[An]] The optoelectronic component as claimed in claim [[5]] 1, wherein the [[said]] base material protrudes outside the plastic package material.

7. (Currently amended) [[An]] The optoelectronic component as claimed in claim 1, wherein the [[said]] base material protrudes to the two other sides (6) toward other side surfaces of the plastic package material, the other side surfaces being used for electrical connections.

8. (Canceled)

9. (New) The optoelectronic component as claimed in claim 1, wherein the external mounting connection terminals are provided without any lead formations.

10. (New) An optoelectronic component based on a surface mount technology, the optoelectronic component comprising:

an electrically conductive frame to form a base for an assembly;
an opaque plastic material to form a housing for the assembly;
a cavity formed within the plastic material;
at least one protrusion extending from a side surface of the housing to provide heat dissipation; and
at least one optoelectronic chip mounted in the cavity,
wherein the electrically conductive frame protrudes from a middle portion to two other side surfaces of the housing, the two other side surfaces of the housing providing external mounting connection terminals.

11. (New) The optoelectronic component as claimed in claim 10, wherein the cavity is filled with a transparent or translucent resin material.

12. (New) The optoelectronic component as claimed in claim 10, wherein the external mounting connection terminals are provided without any lead formations.

13. (New) The optoelectronic component as claimed in claim 10, wherein an electrical connection between the at least one optoelectronic chip and the base is provided by a metallic wire.

14. (New) The optoelectronic component as claimed in claim 10, wherein the external mounting connection terminals are provided for connecting to external subsystems such as PCBs.